

MC14035B

4-Bit Parallel-In/Parallel-Out Shift Register

The MC14035B 4-bit shift register is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. It consists of a 4-stage clocked serial-shift register with synchronous parallel inputs and buffered parallel outputs. The Parallel/Serial (P/S) input allows serial-right shifting of data or synchronous parallel loading via inputs DP0 thru DP3. The True/Complement (T/C) input determines whether the outputs display the Q or \bar{Q} outputs of the flip-flop stages. J-K logic forms the serial input to the first stage. With the J and K inputs connected together they operate as a serial "D" input.

This device may be effectively used for shift-right/shift-left registers, parallel-to-serial/serial-to-parallel conversion, sequence generation, up/down Johnson or ring counters, pseudo-random code generation, frequency and phase comparators, sample and hold registers, etc . . .

- 4-Stage Clocked Serial-Shift Operation
- Synchronous Parallel Loading of all Four Stages
- J-K Serial Inputs on First Stage
- Asynchronous True/Complement Control of all Outputs
- Fully Static Operation
- Asynchronous Master Reset
- Data Transfer Occurs on the Positive-Going Clock Transition
- No Limit on Clock Rise and Fall Times
- All Inputs are Buffered
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range

MAXIMUM RATINGS* (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage	- 0.5 to + 18.0	V
V _{in} , V _{out}	Input or Output Voltage (DC or Transient)	- 0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient), per Pin	± 10	mA
P _D	Power Dissipation, per Package†	500	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
T _L	Lead Temperature (8-Second Soldering)	260	°C

* Maximum Ratings are those values beyond which damage to the device may occur.

† Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

Ceramic "L" Packages: - 12 mW/°C From 100°C To 125°C

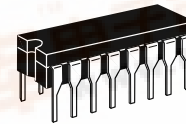
TRUTH TABLE

Inputs				t _n Output Q ₀
C	J	\bar{K}	R	
\swarrow	0	0	0	0
\swarrow	0	1	0	Q ₀ (n - 1)
\swarrow	1	0	0	\bar{Q}_0 (n - 1)
\swarrow	1	1	0	1
\searrow	X	X	0	Q ₀ (n - 1)
\searrow	X	X	1	0

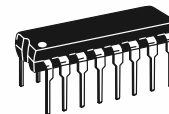
X = Don't Care

P/S = 0 = Serial Mode

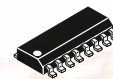
T/C = 1 = True Outputs



L SUFFIX
CERAMIC
CASE 620



P SUFFIX
PLASTIC
CASE 648



D SUFFIX
SOIC
CASE 751B

ORDERING INFORMATION

MC14XXXBCP	Plastic
MC14XXXBCL	Ceramic
MC14XXXBD	SOIC

T_A = - 55° to 125°C for all packages.

PIN ASSIGNMENT

Q0	1	16	V _{DD}
T/C	2	15	Q1
\bar{K}	3	14	Q2
J	4	13	Q3
R	5	12	DP3
C	6	11	DP2
P/S	7	10	DP1
VSS	8	9	DP0

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	- 55 °C		25 °C			125 °C		Unit
			Min	Max	Min	Typ #	Max	Min	Max	
Output Voltage $V_{in} = V_{DD}$ or 0 $V_{in} = 0$ or V_{DD}	"0" Level V_{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
	"1" Level V_{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage ($V_O = 4.5$ or 0.5 Vdc) ($V_O = 9.0$ or 1.0 Vdc) ($V_O = 13.5$ or 1.5 Vdc) ($V_O = 0.5$ or 4.5 Vdc) ($V_O = 1.0$ or 9.0 Vdc) ($V_O = 1.5$ or 13.5 Vdc)	"0" Level V_{IL}	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc
		10	—	3.0	—	4.50	3.0	—	3.0	
		15	—	4.0	—	6.75	4.0	—	4.0	
	"1" Level V_{IH}	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
		10	7.0	—	7.0	5.50	—	7.0	—	
		15	11	—	11	8.25	—	11	—	
Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 4.6$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc) ($V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Source I_{OH}	5.0	- 3.0	—	- 2.4	- 4.2	—	- 1.7	—	mAdc
		5.0	- 0.64	—	- 0.51	- 0.88	—	- 0.36	—	
		10	- 1.6	—	- 1.3	- 2.25	—	- 0.9	—	
		15	- 4.2	—	- 3.4	- 8.8	—	- 2.4	—	
	Sink I_{OL}	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
		10	1.6	—	1.3	2.25	—	0.9	—	
15	4.2	—	3.4	8.8	—	2.4	—	—		
Input Current	I_{in}	15	—	± 0.1	—	± 0.00001	± 0.1	—	± 1.0	μ Adc
Input Capacitance ($V_{in} = 0$)	C_{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	I_{DD}	5.0	—	5.0	—	0.005	5.0	—	150	μ Adc
		10	—	10	—	0.010	10	—	300	
		15	—	20	—	0.015	20	—	600	
Total Supply Current**† (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs all buffers switching)	I_T	5.0	$I_T = (1.0 \mu\text{A/kHz}) f + I_{DD}$							μ Adc
		10	$I_T = (2.0 \mu\text{A/kHz}) f + I_{DD}$							
		15	$I_T = (3.0 \mu\text{A/kHz}) f + I_{DD}$							

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

**The formulas given are for the typical characteristics only at 25 °C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.001$.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

SWITCHING CHARACTERISTICS ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$, See Figure 1)

Characteristic	Symbol	VDD Vdc	Min	Typ #	Max	Unit
Output Rise and Fall Time $T_{TLH}, T_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $T_{TLH}, T_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $T_{TLH}, T_{THL} = (0.55 \text{ ns/pF}) C_L + 12.5 \text{ ns}$	t_{TLH}, t_{THL}	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time, Clock or Reset to Q $T_{PLH}, T_{PHL} = (1.75 \text{ ns/pF}) C_L + 223 \text{ ns}$ $T_{PLH}, T_{PHL} = (0.70 \text{ ns/pF}) C_L + 89 \text{ ns}$ $T_{PLH}, T_{PHL} = (0.53 \text{ ns/pF}) C_L + 67 \text{ ns}$	t_{PLH}, t_{PHL}	5.0 10 15	— — —	300 130 95	600 260 190	ns
Clock Pulse Width	t_{WH}	5.0 10 15	335 165 125	135 45 40	— — —	ns
Reset Pulse Width	t_{WH}	5.0 10 15	400 175 130	80 40 35	— — —	ns
Reset Removal Time	t_{rem}	5.0 10 15	80 30 25	40 15 10	— — —	ns
Clock Pulse Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	No Limit			—
Clock Pulse Frequency	f_{cl}	5.0 10 15	— — —	2.5 6.0 10	1.2 2.0 3.0	MHz
J-K to Clock Setup Time	t_{su}	5.0 10 15	500 200 150	120 50 30	— — —	ns
Clock to J-K Hold Time	t_h	5.0 10 15	40 30 25	-40 -5 0	— — —	ns
P/S to Clock Setup Time	t_{su}	5.0 10 15	500 200 150	25 10 7.5	— — —	ns
Clock to P/S Hold Time	t_h	5.0 10 15	30 20 20	-70 -20 -10	— — —	ns
Dp to Clock Setup Time	t_{su}	5.0 10 15	500 200 150	90 20 15	— — —	ns
Clock to Dp Hold Time	t_h	5.0 10 15	90 40 40	-25 0 5	— — —	ns

* The formulas given are for the typical characteristics only at 25°C.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

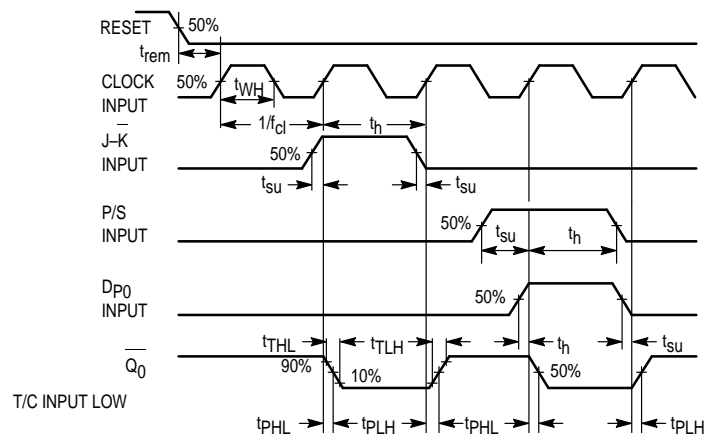
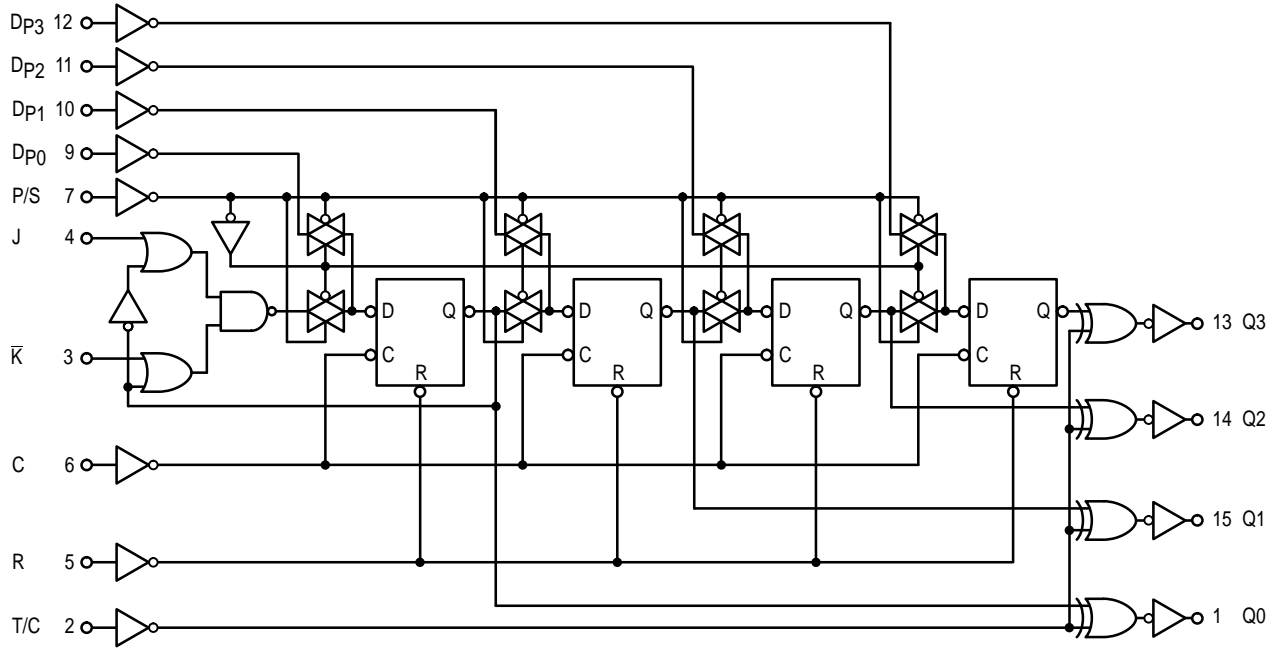
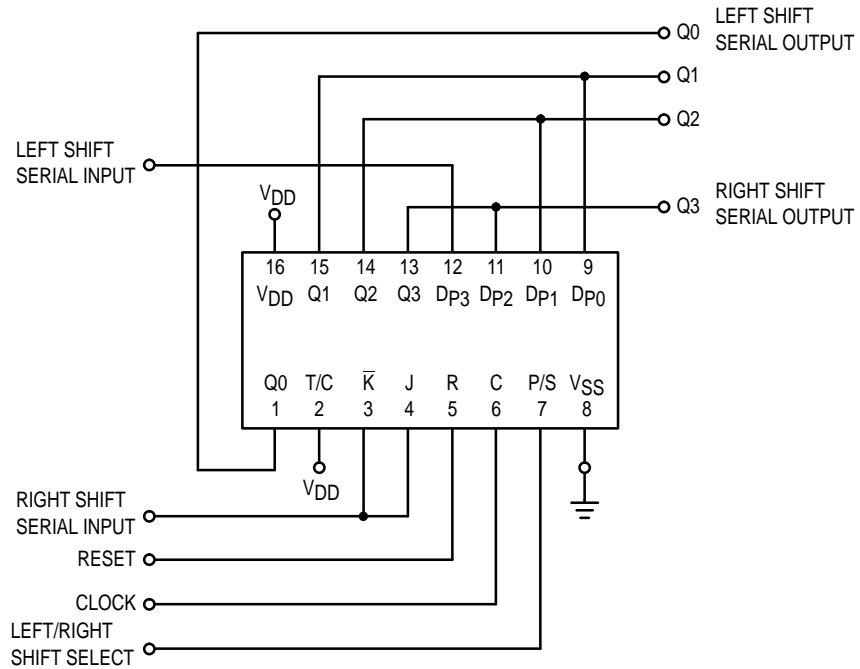


Figure 1. Timing Diagram

LOGIC DIAGRAM

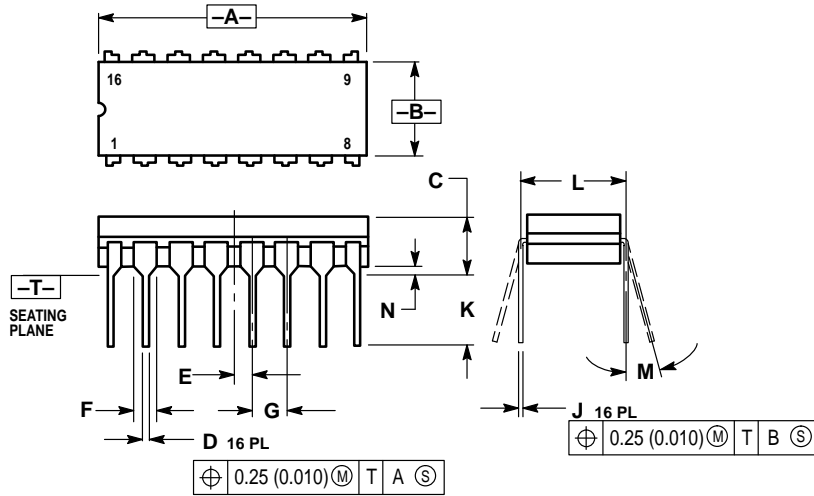


APPLICATION DIAGRAM Shift Left/Shift Right Register



OUTLINE DIMENSIONS

L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V

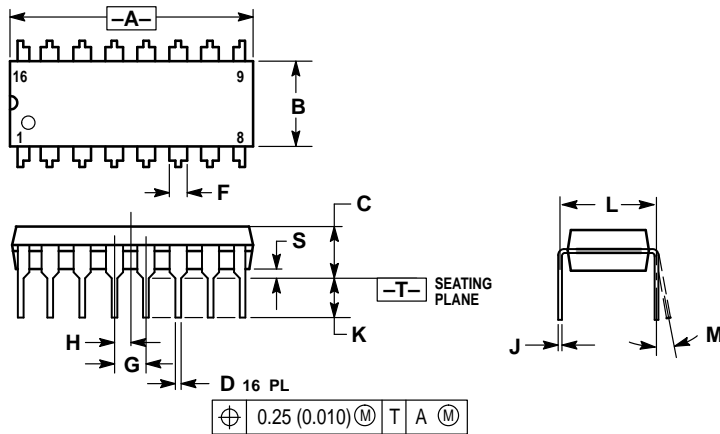


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



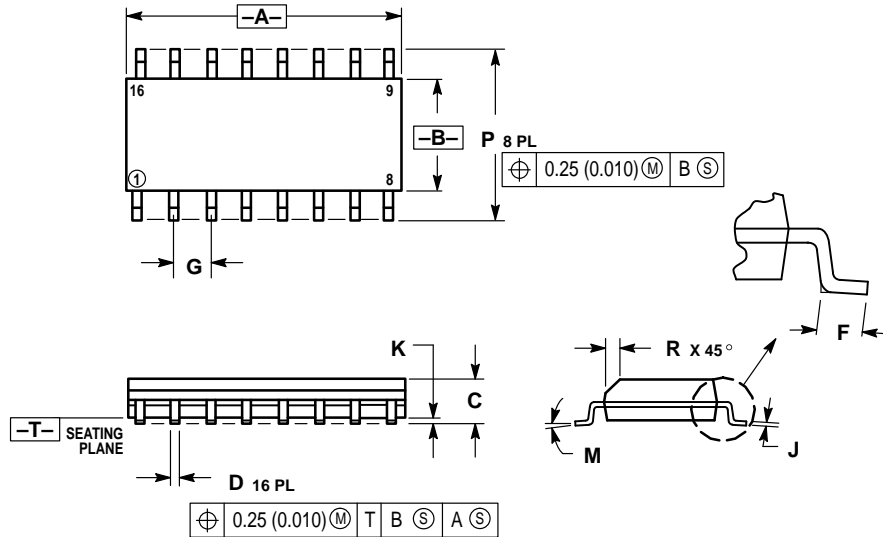
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

OUTLINE DIMENSIONS


D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° 7°		0° 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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